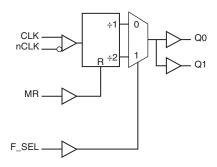
## GENERAL DESCRIPTION

The 87021I is a high performance ÷1/÷2 Differential-to-LVCMOS/LVTTL Clock Generator and a member of the family of High Performance Clock Solutions from IDT. The CLK, nCLK pair can accept most standard differential input levels. Guaranteed part-to-part skew characteristics make the 87021I ideal for those clock distribution applications demanding well defined performance and repeatability.

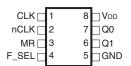
### **F**EATURES

- Two single-ended LVCMOS/LVTTL outputs
- One differential CLK, nCLK input pair
- CLK, nCLK pair can accept the following differential input levels: LVPECL, LVDS, LVHSTL, SSTL, HCSL
- Maximum output frequency: 250MHz
- Additive phase jitter, RMS: 0.18ps (typical)
- Output skew: 50ps (maximum)
- Part-to-part skew: 450ps (maximum)
- Propagation delay: 3.4ns (maximum)
- Full 3.3V or 2.5V operating supply
- -40°C to 85°C ambient operating temperature
- · Availabe in lead-free (RoHS 6) package

## **BLOCK DIAGRAM**



## PIN ASSIGNMENT



87021I
8-Lead SOIC
3.90mm x 4.90mm x 1.375mm package body
M Package
Top View



TABLE 1. PIN DESCRIPTIONS

Number	Name	Ty	/ре	Description
1	CLK	Input	Pulldown	Non-inverting differential clock input.
2	nCLK	Input	Pullup	Inverting differential clock input.
3	MR	Input	Pulldown	Active High Master Reset. When logic HIGH, the internal dividers are reset causing the outputs to go low. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS / LVTTL interface levels. See Table 3.
4	F_SEL	Input	Pulldown	Selects divider value for Qx outputs as described in Table 3. LVCMOS / LVTTL interface levels.
5	GND	Power		Power supply ground.
6	Q1	Output		Singled-ended output. LVCMOS/LVTTL interface levels.
7	Q0	Output		Singled-ended output. LVCMOS/LVTTL interface levels.
8	V <sub>DD</sub>	Power		Positive supply pin.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
C	Power Dissipation Capacitance	V <sub>DD</sub> = 3.465V		24		pF
C <sub>PD</sub>	(per output)	V <sub>DD</sub> = 2.625V		16		pF
R	Input Pullup Resistor			51		kΩ
R	Input Pulldown Resistor			51		kΩ
R <sub>out</sub>	Output Impedance	V <sub>DD</sub> = 3.465V		9		Ω



TABLE 3. FUNCTION TABLE

MR	F_SEL	Divide Value	
1	Х	X Reset: Q0, Q1 outputs low	
0	0	÷1	
0	1	÷2	

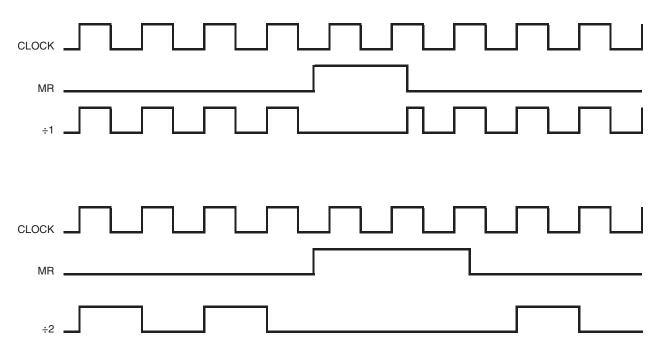


FIGURE 1. TIMING DIAGRAM



#### **ABSOLUTE MAXIMUM RATINGS**

Supply Voltage, V<sub>DD</sub> 4.6V

Inputs,  $V_{pp}$  -0.5 V to  $V_{pp}$  + 0.5 V

Outputs,  $V_{\odot}$  -0.5V to  $V_{DD}$  + 0.5V

Package Thermal Impedance,  $\theta_{_{JA}}$  103°C/W (0 Ifpm)

Storage Temperature, T<sub>STG</sub> -65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 4A. Power Supply DC Characteristics,  $V_{_{DD}}$  =  $3.3V\pm5\%$ , Ta =  $-40^{\circ}C$  to  $85^{\circ}C$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V <sub>DD</sub>	Positive Supply Voltage		3.135	3.3	3.465	V
l <sub>DD</sub>	Power Supply Current				60	mA

Table 4B. Power Supply DC Characteristics,  $V_{DD} = 2.5V \pm 5\%$ , Ta = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V <sub>DD</sub>	Positive Supply Voltage		2.375	2.5	2.625	V
I <sub>DD</sub>	Power Supply Current				35	mA

Table 4C. LVCMOS/LVTTL DC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ , Ta = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage		1.3		V <sub>DD</sub> + 0.3	V
V <sub>IL</sub>	Input Low Voltage		-0.3		0.7	V
I	Input High Current	$V_{DD} = V_{IN} = 3.465V$			150	μA
I <sub>IL</sub>	Input Low Current	$V_{_{DD}} = 3.465V, V_{_{IN}} = 0V$	-5			μΑ
V <sub>OH</sub>	Output High Voltage; NOTE 1	$V_{_{DD}} = 3.465V$	2.6			V
V <sub>OL</sub>	Output Low Voltage; NOTE 1	$V_{DD} = 3.465 \text{V} \text{ or } 2.625 \text{V}$			0.5	V

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{DD}/2$ . See Parameter Measurement Information section,

Table 4D. LVCMOS/LVTTL DC Characteristics, V<sub>DD</sub> = 2.5V±5%, TA = -40°C TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V	Input High Voltage		1.1		V <sub>DD</sub> + 0.3	V
V <sub>IL</sub>	Input Low Voltage		-0.3		0.5	V
I <sub>IH</sub>	Input High Current	$V_{_{DD}} = V_{_{IN}} = 2.625V$			150	μA
I	Input Low Current	$V_{_{DD}} = 2.625V, V_{_{IN}} = 0V$	-5			μΑ
V <sub>OH</sub>	Output High Voltage; NOTE 1	V <sub>DD</sub> = 2.625V	1.8			V
V <sub>OL</sub>	Output Low Voltage; NOTE 1	$V_{_{DD}} = 2.625V$			0.5	V

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{nn}/2$ . See Parameter Measurement Information section,

<sup>&</sup>quot;3.3V Output Load Test Circuit" diagram.

<sup>&</sup>quot;2.5V Output Load Test Circuit" diagram.



 $\textbf{Table 4E. Differential DC Characteristics, V}_{\tiny DD} = 3.3V \pm 5\% \quad \text{or V}_{\tiny DD} = 2.5V \pm 5\%, \, \text{Ta} = -40 ^{\circ}\text{C to } 85 ^{\circ}\text{C}$ 

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
	Input High Current	CLK	$V_{DD} = V_{IN} = 3.465 \text{V or } 2.625 \text{V}$			150	μΑ
<b>'</b> н		nCLK	$V_{DD} = V_{IN} = 3.465 \text{V or } 2.625 \text{V}$			5	μΑ
,	Input Low Current	CLK	$V_{DD} = 3.465 \text{V or } 2.625 \text{V}, V_{IN} = 0 \text{V}$	-5			μΑ
I <sub>IL</sub>	Imput Low Current	nCLK	$V_{DD} = 3.465 \text{V or } 2.625 \text{V}, V_{IN} = 0 \text{V}$	-150			μA
V	Peak-to-Peak Input \	/oltage		0.15		1.3	V
V <sub>CMR</sub>	Common Mode Inpu NOTE 1	t Voltage;		GND + 0.5		V <sub>DD</sub> - 0.85	V

NOTE 1: Common mode voltage is defined as  $V_{_{\rm II}}$ .

**Table 5A. AC Characteristics,**  $V_{dd} = 3.3V \pm 5\%$ , Ta = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency					250	MHz
t <sub>PD</sub>	Propagation Delay; NOTE 1	CLK to Qx		2.1		3.4	ns
<i>t</i> jit	Buffer Additive Phase refer to Additive Phase tion		250MHz, Integration Range: 12kHz – 20MHz		0.18		ps
tsk(pp)	Part-to-Part Skew; NO	TE 2, 3				450	ps
tsk(o)	Output Skew; NOTE 3	4				50	ps
t <sub>R</sub> / t <sub>F</sub>	Output Rise/Fall Time		20% to 80%	250		700	ps
odc	Output Duty Cycle;		Fout ≤ 133MHz	45		55	%
louc	Output Duty Cycle,	NOTE 5	Fout > 133MHz	40		60	%

NOTE 1: Measured from the differential input crossing point to the output at  $V_{pp}/2$ .

NOTE 2: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at V /2.

NOTE 3: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 4: Defined as skew between outputs at the same supply voltage and with equal load conditions.

NOTE 5: Output Duty Cycle assuming 50% input duty cycle.

**Table 5B. AC Characteristics,**  $V_{DD} = 2.5V \pm 5\%$ , Ta = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency					250	MHz
t <sub>PD</sub>	Propagation Delay; NOTE 1	CLK to Qx		2.7		3.4	ns
<i>t</i> jit	Buffer Additive Phase refer to Additive Phase tion		250MHz, Integration Range: 12kHz – 20MHz		0.3		ps
tsk(pp)	Part-to-Part Skew; NO	TE 2, 3				450	ps
tsk(o)	Output Skew; NOTE 3	, 4				25	ps
t <sub>R</sub> / t <sub>F</sub>	Output Rise/Fall Time		20% to 80%	250		700	ps
odc	Output Duty Cycle;		Fout ≤ 133MHz	45		55	%
louc	Output Duty Cycle,	NOTE 5	Fout > 133MHz	40		60	%

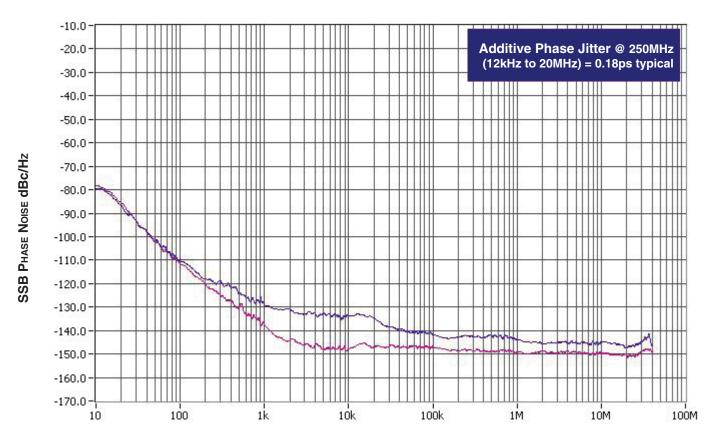
For NOTES, please see above Table 5A.



## **ADDITIVE PHASE JITTER**

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the *dBc Phase Noise*. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels

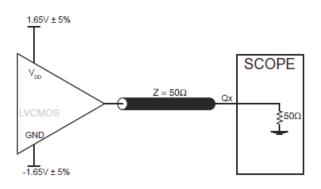
(dBm) or a ratio of the power in the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a *dBc* value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



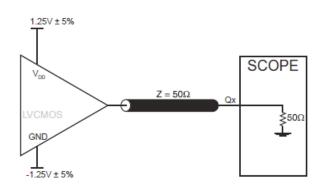
OFFSET FROM CARRIER FREQUENCY (Hz)



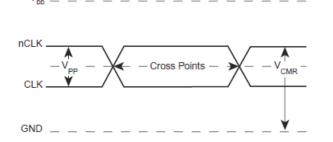
## PARAMETER MEASUREMENT INFORMATION

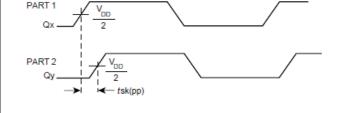


## 3.3V OUTPUT LOAD AC TEST CIRCUIT



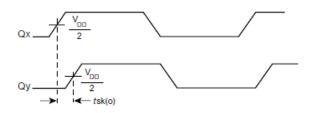
2.5V OUTPUT LOAD AC TEST CIRCUIT

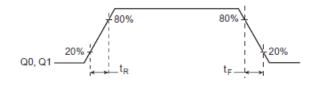




#### DIFFERENTIAL INPUT LEVEL

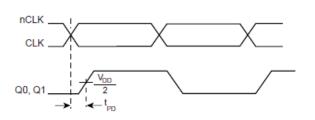


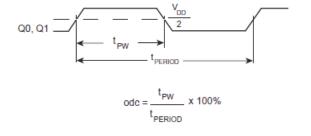




#### **OUTPUT SKEW**

### OUTPUT RISE/FALL TIME





## PROPAGATION DELAY

## OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD



## **APPLICATION INFORMATION**

#### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage  $V_REF = V_{DD}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio

of R1 and R2 might need to be adjusted to position the V\_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{\tiny DD}=3.3V, V_{\tiny ABF}$  should be 1.25V and R2/R1 = 0.609.

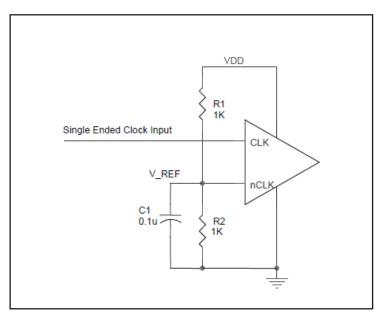


FIGURE 1. SINGLE ENDED SIGNAL DRIVING DIFFERENTIAL INPUT

#### RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

#### INPUTS:

#### LVCMOS CONTROL PINS

All control pins have internal pullups or pulldowns; additional resistance is not required but can be added for additional protection. A  $1k\Omega$  resistor can be used.

#### **OUTPUTS:**

#### **LVCMOS OUTPUTS**

All unused LVCMOS output can be left floating. There should be no trace attached.



#### DIFFERENTIAL CLOCK INPUT INTERFACE

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both signals must meet the  $V_{\text{PP}}$  and  $V_{\text{CMR}}$  input requirements. Figures 2A to 2E show interface examples for the HiPerClockS CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are examples only.

Please consult with the vendor of the driver component to confirm the driver termination requirements. For example in *Figure 2A*, the input termination applies for IDT HiPerClockS LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

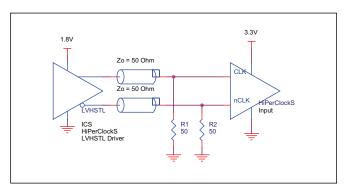


FIGURE 2A. HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY IDT HIPERCLOCKS LVHSTL DRIVER

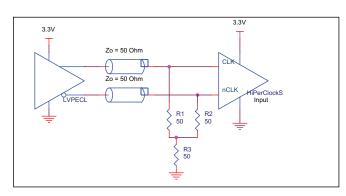


FIGURE 2B. HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

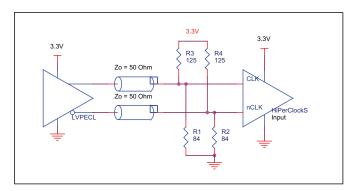


FIGURE 2C. HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

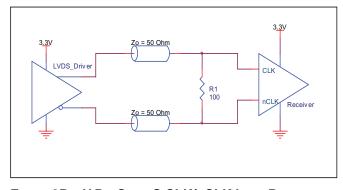


FIGURE 2D. HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVDS DRIVER

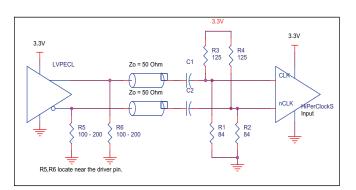


FIGURE 2E. HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER WITH AC COUPLE



## RELIABILITY INFORMATION

## Table 6. $\theta_{_{JA}} vs.$ Air Flow Table for 8 Lead SOIC

## $\theta_{\text{\tiny JA}}$ by Velocity (Linear Feet per Minute)

0200500Single-Layer PCB, JEDEC Standard Test Boards123°C/W110°C/W99°C/WMulti-Layer PCB, JEDEC Standard Test Boards103°C/W94°C/W89°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

#### **TRANSISTOR COUNT**

The transistor count for 87021I is: 414



### PACKAGE OUTLINE - M SUFFIX FOR 8 LEAD SOIC

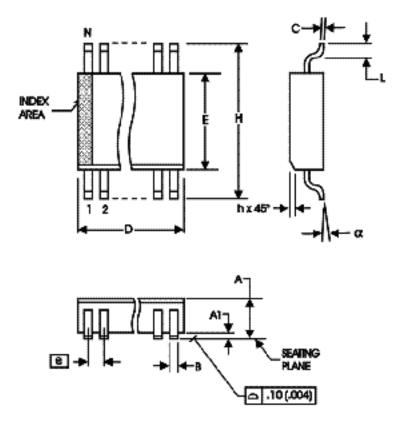


TABLE 7. PACKAGE DIMENSIONS

CVMPOL	Millin	neters
SYMBOL	MINIMUN	MAXIMUM
N	8	3
Α	1.35	1.75
A1	0.10	0.25
В	0.33	0.51
С	0.19	0.25
D	4.80	5.00
E	3.80	4.00
е	1.27 E	BASIC
Н	5.80	6.20
h	0.25	0.50
L	0.40	1.27
α	0°	8°

Reference Document: JEDEC Publication 95, MS-012



## Table 8. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
87021AMILF	87021AIL	8 lead "Lead Free" SOIC	Tray	-40°C to +85°C
87021AMILFT	87021AIL	8 lead "Lead Free" SOIC	Tape and Reel	-40°C to +85°C



REVISION HISTORY SHEET				
Rev	Table	Page	Description of Change	Date
В	T2	2	Pin Characteristics Table - added R <sub>ουτ</sub> row.	8/26/08
В	Т8	1 1 12	Removed ICS from the part numbers where needed. General Description - Removed the ICS chip and HiPerClockS. Features Section - Removed reference to lead free packages. Ordering Information - removed quantity from tape and reel. Deleted LF note below the table. Updated header and footer.	1-26-16





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